



Material Content Data Sheet



Sales Product Name		SAK-TC1766-192F80HL BD		Issued		19. January 2018		
MA#		MA001646914						
Package		PG-LQFP-176-14		Weight*		2045.21 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	36.463	1.78	1.78	17828	17828
leadframe	non noble metal	magnesium	7439-95-4	0.746	0.04		365	
	inorganic material	silicon	7440-21-3	3.234	0.16		1581	
	non noble metal	nickel	7440-02-0	14.926	0.73		7298	
	non noble metal	copper	7440-50-8	478.622	23.40	24.33	234021	243265
wire	noble metal	gold	7440-57-5	3.526	0.17	0.17	1724	1724
encapsulation	organic material	carbon black	1333-86-4	4.452	0.22		2177	
	plastics	epoxy resin	-	136.527	6.68		66754	
	inorganic material	silicondioxide	60676-86-0	1343.008	65.66	72.56	656662	725593
leadfinish	non noble metal	tin	7440-31-5	15.144	0.74	0.74	7405	7405
plating	noble metal	silver	7440-22-4	2.988	0.15	0.15	1461	1461
glue	plastics	epoxy resin	-	1.393	0.07		681	
	noble metal	silver	7440-22-4	4.178	0.20	0.27	2043	2724
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com